

SUPPLEMENTARY INFORMATION: Polymers for Near-field Electrospinning with Spatial Control

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Table 1: Electrospun Polymer Solutions - Solution and Process Parameters

Polymer(s)	Solvent(s)	NFES Variant	Process Parameters and Fiber Characterization	Ref.
Poly(ethylene oxide) (PEO; MW = 4,000,000 g/mol)	Deionized water	Low-Voltage NFES (LV NFES)	Solution Concentration: 1, 2, and 3 wt% PEO Nozzle: 27 gauge type 304; stainless steel needle Solution deposition rate: lower than $1\mu L/h$ Nozzle-to-substrate distance: 1mm Substrate composition: Pyrolyzed SU-8 carbon and Si Applied voltage: polymer jet initiated at 400-600 V and dispensed at 200-400 V x-y stage velocity: 10-40mm/s Fiber Diameter: 50-425nm Distance between adjacent fibers: <i>Not determined</i>	[1]

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<i>Table 1 continued</i>				
Poly[2-methoxy-5-(2-ethylhexyloxy)-1,4-phenylenevinylene] (MEH-PPV; MW = 380,000 g/mol) with Poly(ethylene oxide) (PEO; MW = 300,000 g/mol)	acetonitrile toluene mixture (65/35); acetic acid toluene (17/83); pure toluene	Typical process	NFES	Solution Concentration: 10mg of MEH-PPV in 2mL of toluene; 500 μ L of MEH-PPV solution with 250mg of PEO in 3.5mL of acetonitrile / toluene (65 / 35); 500 μ L of MEH-PPV solution with 250mg of PEO in 3mL of acetic acid / toluene (17 / 83). The resulting MEH-PPV/PEO concentration is 0.08 wt% Nozzle: mm-diameter tip Tungsten spinneret in a 26 gauge needle Solution deposition rate: 50 μ L/h Nozzle-to-substrate distance: 500 μ m Substrate composition: SiO ₂ /Si (oxide thickness = 800 nm) Applied voltage: around 1.3kV x-y stage velocity: 50cm/s Fiber Diameter: 100nm Distance between adjacent fibers: around 100 μ m

[2]

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<i>Table 1 continued</i>			
Poly(ethylene oxide) (PEO; MV = 300,000 <i>g/mol</i>)	Water	Scanning Tip Electrospinning and NFES	<p>Solution Concentration: 7wt% PEO [3]</p> <p>Nozzle: Needle outer diameter of 200μm and inner diameter of 100μm</p> <p>Solution deposition rate: 0.1μL/h</p> <p>Nozzle-to-substrate distance: 500μm</p> <p>Substrate composition: <i>Not determined</i></p> <p>Applied voltage: polymer jet initiated at 1.5 <i>kV</i> and dispensed at 600V</p> <p>x-y stage velocity: 120mm/s</p> <p>Fiber Diameter: 709\pm131nm; 49-74nm when applied voltage is 800V</p> <p>Distance between adjacent fibers: <i>Not determined</i></p> <p>Notes: 108m yield in 15min with a fiber diameter of 709\pm131nm</p>
Poly(vinylidene fluorid) (PVDF; MW = 440,000 <i>g/mol</i>)	N,N Dimethyl-formamide (DMF)	Helix Electrohydrodynamic Printing (HE-printing)	<p>Solution Concentration: 1.8g PVDF in 4.1g of DMF and 4.1g of acetone. The resulting concentration is 18% PVDF. [4]</p> <p>Nozzle: Needle outer diameter of 510μm and inner diameter of 260μm</p> <p>Solution deposition rate: 400nL/min</p> <p>Nozzle-to-substrate distance: 10-50mm</p> <p>Substrate composition: Poly(dimethylsiloxane) (PDMS) on Ecoflex</p> <p>Applied voltage: 1.5–3kV</p> <p>x-y stage velocity: 0-400mm/min</p> <p>Fiber Diameter: about 1.5-3μm</p> <p>Distance between adjacent fibers: <i>Not determined</i></p>

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<i>Table 1 continued</i>				
Polyhedral Oligomeric Silsesquioxane-Poly(Carbonate-Urea)Urethane (POSS-PCU) and Polyhedral Oligomeric Silsesquioxane Poly(Caprolactone-Poly(Carbonate-Urea)Urethane) (POSS-PCL-PCU) (Dry Polycarbonate MW = 2000 g/mol)	Dimethyl acetamide (DMAC) and 1-Butanol	Electrohydro-dynamic 3D Print-patterning or Electrohydro-dynamic Jetting	Solution Concentration: POSS-PCU and POSS-PCL-PCU used in 20%w/w concentration in DMAC Nozzle: needle of 750 μm in diameter Solution deposition rate: less than 1 $\mu L/min$ Nozzle-to-substrate distance: about between 500 μm to 2mm Substrate composition: <i>Not determined</i> Applied voltage: 8.0-10.0kV x-y stage velocity: 10mm/s Fiber Diameter: 15-50 μm Distance between adjacent fibers: 250 μm	[5]
Poly(ethylene oxide) (PEO; MW = 300,000 g/mol)	Distilled water	Electrohydro-dynamic Writing or Mechano-electrospinning (MES)	Solution Concentration: 6wt% PEO Nozzle: <i>Not determined</i> Solution deposition rate: 1200nL/min Nozzle-to-substrate distance: 7.5mm Substrate composition: <i>Not determined</i> Applied voltage: polymer jet initiated at 2 kV and dispensed at 0.8-1kV x-y stage velocity: around 400mm/s Fiber Diameter: 200-350nm Distance between adjacent fibers: 5 μm	[6]

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<i>Table 1 continued</i>				
Poly(ethylene oxide) (PEO; MW = 300,000 <i>g/mol</i>)	Deionized water and ethanol with a volume ratio of 3:1	Airflow-assisted Electrohydrodynamic Direct-writing (EDW)	Solution Concentration: 8wt% PEO Nozzle: Outer airflow passage diameter: 1mm Airflow gas pump pressure: 25kPa Inner liquid passage diameter: 0.21mm Solution deposition rate: 30 μ L/h Nozzle-to-substrate distance: 2mm Substrate composition: Silicon Applied voltage: about 2kV x-y stage velocity: 1-20mm/s Fiber Diameter: 3.73 \pm 1.37 μ m Distance between adjacent fibers: 5.13 \pm 6.67 μ m	[7]
Poly(Vinylidene Fluoride) (PVDF; MW = 534,000 <i>g/mol</i>)	Acetone and Dimethyl Sulfoxide (DMSO)	3D Electrospinning	Solution Concentration: 17wt% PVDF; 1.7g of PVDF, 5g of acetone, 0.5g of Capstone FS-66, 5g of DMSO Nozzle: Needle inner diameter of 100 μ m Solution deposition rate: 14 nL/min Nozzle-to-substrate distance: 750 μ m Substrate composition: A4 size commercial printing paper (Double A) Applied voltage: 1.9kV x-y stage velocity: 10mm/s Fiber Diameter: Not determined Distance between adjacent fibers: Not determined	[8]

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<i>Table 1 continued</i>				
Poly(9-Vinyl Carbazole) (PVK; MW = 1,100,000 g/mol)	Styrene	Typical process	NFES	Solution Concentration: 3.96wt% PVK in styrene [9] Nozzle: Needle inner diameter of 100 μ m Solution deposition rate: 500nL/min Nozzle-to-substrate distance: around 2.5mm Substrate composition: Si/SiO ₂ Applied voltage: 3-4kV x-y stage velocity: 13.3cm/s Fiber Diameter: 289.26 \pm 35.37nm Distance between adjacent fibers: 50 μ m Notes: 15m yield in 2min
Polystyrene (PS; MW <i>Not determined</i>)	1,2,4-Trichloro benzene	Electrohydrodynamic (EHD) jet printing		Solution Concentration: 1 to 5wt% PS [10] Nozzle: Glass nozzle inner diameter of 2 μ m and outer diameter of 2.66 μ m Solution deposition rate: <i>Not determined</i> Nozzle-to-substrate distance: 20, 30, 40 μ m Substrate composition: Si Applied voltage: 500 to 400V in 25V increments x-y stage velocity: 0.01-10mm/s Fiber Diameter: about 60-170 μ m Distance between adjacent fibers: <i>Not determined</i>
Poly(ethylene oxide) (PEO; MW = 300,000 g/mol)	<i>Not determined</i>	Typical process	NFES	Solution Concentration: 3wt% PEO [11] Nozzle: <i>Not determined</i> Solution deposition rate: <i>Not determined</i> Nozzle-to-substrate distance: 500 μ m Substrate composition: Si Applied voltage: 1000V x-y stage velocity: 20cm/s Fiber Diameter: 300nm Distance between adjacent fibers: 25 μ m

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<i>Table 1 continued</i>				
Poly(ethylene oxide) (PEO; MW = 2,000,000 g/mol)	Distilled water		Multinozzle NFES	Solution Concentration: 5wt% [12] Nozzle: four-nozzle and six-nozzle array with needle spacing changes from 1.5mm to 3.5mm Solution deposition rate: 1-3 μ L/min Nozzle-to-substrate distance: 2mm Substrate composition: <i>Not determined</i> Applied voltage: 1.7-2.7kV x-y stage velocity: <i>Not determined</i> Fiber Diameter: 5.47 μ m Distance between adjacent fibers: 3-5 mm
Poly(ethylene oxide) (PEO; MW = 2,000,000 g/mol)	Distilled water		Multinozzle NFES	Solution Concentration: 5wt% [13] Nozzle: Dual-28G-needle array with needle inner diameter of 0.18mm and outer diameter of 0.36mm; with needle spacing changes from 2.0mm to 3.0mm Solution deposition rate: 0.2 μ L/min Nozzle-to-substrate distance: 3.0-4.0mm Substrate composition: <i>Not determined</i> Applied voltage: 2.0-3.0kV x-y stage velocity: 20mm/s Fiber Diameter: <i>Not determined</i> Distance between adjacent fibers: 218-326 μ m

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<i>Table 1 continued</i>				
Poly(ethylene oxide) (PEO; MW = 2,000,000 g/mol)	Distilled water	Multinozzle NFES		Solution Concentration: 5 wt% Nozzle: Dual-28G-needle array with needle inner diameter of 180 μ m and outer diameter of 360 μ m; with needle spacing changes of 2.0mm Solution deposition rate: 0.2 μ L/min Nozzle-to-substrate distance: 4.0mm Substrate composition: chromium-plated glass Applied voltage: 2.5kV x-y stage velocity: 20mm/s Fiber Diameter: Not determined Distance between adjacent fibers: 2.3002-2.7224mm
Poly(ethylene oxide) (PEO; MW = 4,000,000 g/mol)	Not determined	Typical process	NFES	Solution Concentration: 2wt% Nozzle: G30 needle with inner diameter of 0.15mm Solution deposition rate: Not determined Nozzle-to-substrate distance: 1-3mm Substrate composition: Silicon Applied voltage: 1250V x-y stage velocity: Not determined Fiber Diameter: Not determined Distance between adjacent fibers: 20 μ m

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<i>Table 1 continued</i>				
Gelatin (porcine skin; MW <i>Not determined</i>)	Acetic and Acetate	Acid Ethyl	Typical process	NFES
Solution Concentration: 11wt% gelatin, 30wt% water, 35.4wt% acetic acid, 23.6wt% ethyl acetate Nozzle: 19G needle tip with outer diameter of 1.08mm Solution deposition rate: <i>Not determined</i> Nozzle-to-substrate distance: 1.25mm Substrate composition: Poly(Dimethylsiloxane) (PDMS) films Applied voltage: 1000V x-y stage velocity: <i>Not determined</i> Fiber Diameter: around 2-3 μ m Distance between adjacent fibers: 40 μ m				
Poly(ethylene oxide) (PEO; MW = 300,000 g/mol)	Water/Ethanol (v/v = 60/40)		Typical process	NFES
Solution Concentration: PEO concentrations of 16% and 18% Nozzle: 40 μ m Solution deposition rate: <i>Not determined</i> Nozzle-to-substrate distance: 1mm Substrate composition: Planar silicon Applied voltage: 1.7kV x-y stage velocity: 0.36m/s Fiber Diameter: 5.15 μ m Distance between adjacent fibers: <i>Not determined</i>				

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<i>Table 1 continued</i>			
Poly(ethylene oxide) (PEO; MW = 300,000 <i>g/mol</i>)	Water/Ethanol (v/v = 3/1)	Electrohydrodynamic Direct-Write (EDW)	<p>Solution Concentration: 14wt% PEO [18]</p> <p>Nozzle: Stainless needle with inner diameter of 210μm and outer diameter of 400μm</p> <p>Solution deposition rate: 50$\mu L/h$</p> <p>Nozzle-to-substrate distance: 2mm</p> <p>Substrate composition: Poly(ethylene terephthalate) (PET)</p> <p>Applied voltage: 3kV</p> <p>x-y stage velocity: 700mm/s</p> <p>Fiber Diameter: 15-35μm</p> <p>Distance between adjacent fibers: 70μm</p>
Poly(ethylene oxide) (PEO; MW = 300,000 <i>g/mol</i>)	Deionized water	Mechano-Electrospinning	<p>Solution Concentration: 3wt% PEO [19]</p> <p>Nozzle: Stainless steel nozzle with inner diameter of 160μm and outer diameter of 310μm</p> <p>Solution deposition rate: 50nL/min</p> <p>Nozzle-to-substrate distance: 2-5mm</p> <p>Substrate composition: Silicone</p> <p>Applied voltage: polymer jet initiated at 2kV and dispensed at 1kV</p> <p>x-y stage velocity: 200-400mm/s</p> <p>Fiber Diameter: from 344\pm32 to 214\pm27nm</p> <p>Distance between adjacent fibers: Not determined</p>

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<i>Table 1 continued</i>				
Poly(co-Glycolic acid (PLGA; MW <i>Not determined</i>)	Dimethyl Carbonate (DMC)	Tethered Electrohydrodynamic Spinning (TPES)	Pyro-	Solution Concentration: <i>Not determined</i> [20] Nozzle: nozzle-free Solution deposition rate: The drop reservoir is placed directly on a flat substrate Nozzle-to-substrate distance: Taylor's cone is focused and put in direct contact with the collector Substrate composition: Poly(tetrafluoroethylene) (PTFE) coated glass slide Applied voltage: pyro-electric field of between 2.7×10^7 V/m and 5.5×10^7 V/m x-y stage velocity: <i>Not determined</i> Fiber Diameter: 304.7nm Distance between adjacent fibers: <i>Not determined</i>
Poly(ethylene oxide) (PEO; MW = 4,000,000 g/mol) with Tetrabutylammonium tetrafluoroborate (TBF; MW <i>Not determined</i>) and SU-8 2002	N,N-Dimethylformamide (DMF)	Typical process	NFES	Solution Concentration: SU-8/PEO/TBF blend with 0.75wt% PEO, 1wt% TBF; the blend is diluted with 30vol% DMF $\mu m \mu m$ [21] Solution deposition rate: <i>Not determined</i> Nozzle-to-substrate distance: <i>Not determined</i> Substrate composition: Brass disk with a diameter of 38mm Applied voltage: 980V x-y stage velocity: <i>Not determined</i> Fiber Diameter: <i>Not determined</i> Distance between adjacent fibers: <i>Not determined</i>

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<i>Table 1 continued</i>				
Poly(ethylene oxide) (PEO; 200,000 <i>g/mol</i>)	Water:Ethanol (3:2)	Suspension	NFES	Solution Concentration: 14wt% PEO [22] Nozzle: stainless steel needle (25 G) with inner diameter of 0.25mm Solution deposition rate: 3nL/s Nozzle-to-substrate distance: between 0.5 and 10mm with 0.5mm increments Substrate composition: Planar silicon electrodes Applied voltage: 1.6kV x-y stage velocity: 50, 150, and 250mm/s Fiber Diameter: 300nm Distance between adjacent fibers: 0.1 and 0.5mm
Poly(ethylene oxide) (PEO; MW = 400,000 <i>g/mol</i>)	Deionized water	Typical process	NFES	Solution Concentration: 10wt% PEO [23] Nozzle: 32G metal needle Solution deposition rate: (Jet impact speed of 5mm/s) Nozzle-to-substrate distance: 0.5mm Substrate composition: p-type silicon wafer Applied voltage: 400V x-y stage velocity: 5mm/s Fiber Diameter: <i>Not determined</i> Distance between adjacent fibers: 50μm

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